

Date: February 2020
Rev: XII
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.80
Pot Life: 28 Days
Shelf Life: One year at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 125°C / 2 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® T6067-3 is a single component thermally conductive epoxy for hybrid die and component attach. It can also be used for semiconductor and high temperature ceramic and vacuum packaging. It is a lower viscosity version of EPO-TEK® T6067.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
 Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	White		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 1 rpm:	100,000-150,000	cPs	
Thixotropic Index:	4.1		
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	47	x 10 ⁻⁶ in/in°C
	Above Tg:	167	x 10 ⁻⁶ in/in°C
Shore D Hardness:	89		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 25	Kg	8,890 psi
Degradation Temp:	403	°C	
Weight Loss:			
	@ 200°C:	0.06	%
	@ 250°C:	0.44	%
	@ 300°C:	0.90	%
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Storage Modulus:	495,349	psi	
Ion Content:	Cl:	195 ppm	Na ⁺ : 7 ppm
	NH ₄ ⁺ :	70 ppm	K ⁺ : 14 ppm
* Particle Size:		≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.0	W/mK
Volume Resistivity @ 23°C:	≥ 2 x 10 ¹³	Ohm-cm
Dielectric Constant (1KHz):	3.33	
Dissipation Factor (1KHz):	0.011	

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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EPO-TEK® T6067-3 Advantages & Suggested Application Notes:

- A high viscosity and thixotropic paste suitable for dispensing, screen printing or manual hand application.
- Performs exceptionally well as a die-attach for small chips such as GaAs, LEDs, diodes and SMD components.
- Capable of resisting 260° C reflow processes, low outgassing hermetic lid seal processes, and organic burn-in up to 150° C/1000 hour storage.
- Capable of JEDEC Level II die attach packaging on die paddles and lead frames.
- Popular for non-electrically conductive die attach capable of bonding to a wide range of substrates including kovar ceramic and BT.
- Available in a higher viscosity version; T6067.
- Can be used as a non-conductive stacking epoxy, in conjunction with E3037, for attaching SMD in hybrid and other packages.

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